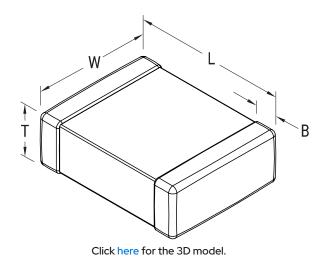


CBR04C608B3GAC

Specifications Capacitance

CBR-SMD RF COG, Ceramic, 0.6 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

T&R, 180mm, Plastic Tape

10000

Packaging Specifications	
Packaging	

Packaging Quantity

+/-0.1 pF Tolerance Voltage DC 25 VDC **Dielectric Withstanding Voltage** 62.5 VDC -55/+125°C **Temperature Range** Temp. Coefficient COG 0.24% **Dissipation Factor** 0% Loss/Decade Hour Aging Rate Insulation Resistance 10 GOhms **Quality Factor** 412

0.6 pF

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